

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("20010008775").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/06/07 13:29
L2	1	("6838319").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/06/07 13:34
L3	5	((("6295221") or ("20010050846") or ("6404643") or ("6753567") or ("re38068"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/06/07 14:06
L4	32	"6295221" "20010050846" "6404643" "6753567" re38068	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 13:36
L5	23	L4 and card	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 13:40
L6	6	I5 and (@ad<"20010611")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 14:19
L7	5	((("6295221") or ("20010050846") or ("6404643") or ("6753567") or ("re38068"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/06/07 14:06
L8	3	I6 and (push or move or lower)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 14:34
L9	4617	(@ad<"20010611") and ("IC" or semiconductor or chip or die) and card and (encapsulant or epoxy or encapsulate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 14:59
L10	3707	I9 and (push or move or lower or move or thrust or shove or exert or force or ram)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 15:33

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L11	1065	L10 and (mold or molding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 14:38
L12	565	L11 and (strip or frame)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 14:38
L13	105	361/737.ccls. and ((die or chip with (down or up or push or move or lower or move or thrust or shove or exert or force or ram))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 14:58
L14	26	L13 and (@ad<"20010611") and (encapsulant or epoxy or encapsulate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 14:59
L15	421	(@ad<"20010611") and 438/15,25, 26,51,55.ccls. and (encapsulate or mold or molding or epoxy or resin or plastic or encapsulation) and (push or move or lower or move or thrust or shove or exert or force or ram)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 15:35
L16	36	(@ad<"20010611") and 438/15,25, 26,51,55.ccls. and (encapsulate or mold or molding or epoxy or resin or plastic or encapsulation) and (push or move or lower or move or thrust or shove or exert or force or ram) and card	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 15:36
L17	208	(@ad<"20010611") and 257/666, 679.ccls. and (encapsulate or mold or molding or epoxy or resin or plastic or encapsulation) and (push or move or lower or move or thrust or shove or exert or force or ram) and card	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 15:37

## EAST Search History

L18	0	(@ad<"20010611") and "361,736, 737,752,816".ccls. and (encapsulate or mold or molding or epoxy or resin or plastic or encapsulation) and (push or move or lower or move or thrust or shove or exert or force or ram) and card	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 15:37
L19	493	(@ad<"20010611") and 361/736, 737,752,816.ccls. and (encapsulate or mold or molding or epoxy or resin or plastic or encapsulation) and (push or move or lower or move or thrust or shove or exert or force or ram) and card	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/07 15:37